

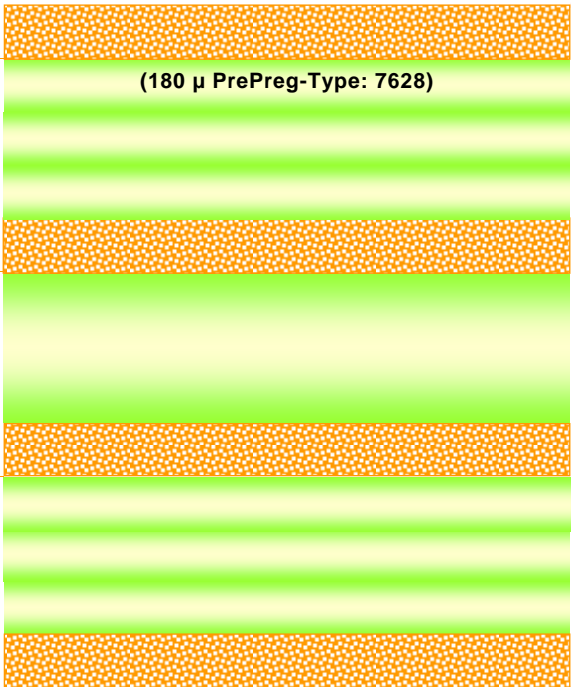
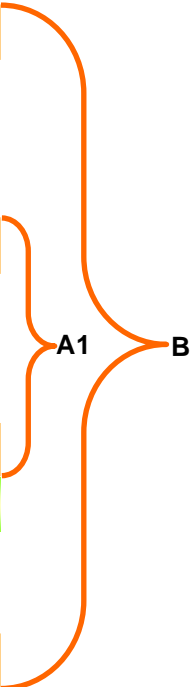
**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 219 FR4 95 L71.105 P18**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_219\_FR4\_95\_L71.105\_p18**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	95 $\mu$	Copper			
	180 $\mu$	Prepreg			(180 $\mu$ PrePreg-Type: 7628)
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
<b>Layer-2</b>	105 $\mu$	Copper			
	710 $\mu$	L-FR4			
<b>Layer-3</b>	105 $\mu$	Copper			
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
<b>Layer-99</b>	95 $\mu$	Copper			

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